



# ELPOX SC 65MN

*ELECTRICALLY CONDUCTIVE SINGLE COMPONENT ADHESIVE*

- \* **ELECTRICALLY CONDUCTIVE**
- \* **HIGH TEMPERATURE RESISTIVE FORMULATION**
- \* **EPOXY-PHENOLIC HYBRIDE TYPE BINDER**

## **GENERAL DESCRIPTIONS:**

**ELPOX SC 65MN** is single component, electrically conductive, silver filled, epoxy-phenolic base resin adhesive. This paste is especially prepared for die attached application and making connections to copper material. It can be also use for through hole double sided PCB applications.

**ELPOX SC 65MN** has high and stable electrical conductivity. This type is mostly for high-speed technological process. It doesn't change viscosity even on open area with thin layer.

## **SPECIFICATIONS:**

Number of components	One
Consistency	Floable paste
Color	Bright silver
Percentage of silver (inside ready paste)	65 ± 1%
Specific gravity	2.1 – 2.4 g/cm <sup>3</sup>
Viscosity	245 000 – 265 000 cps (*)
Drying time before curing process	Not necessary
Recommended curing schedule with air-circulated oven	180°C – (40 – 60) min. 200°C – 20 min.
Recommended curing schedule with heating tunnel	200°C in peak – 10 min. total time inside tunnel.
Shelf life	6 months (when storage at 10°C – unopened)

(\*) - Brookfield DVII; SSA#14; 1 rpm; 25°C.

## **TECHNICAL PROPERTIES (\*):**

Electrical resistivity	(4.0 –5.5) x E(-6) Ωm
Pencil hardness	9H pencil hardness (one day after curing)
Range of service for continuos temperature	(-55)°C - (+200)°C
Max. operating temperature	Over 300°C for a several min.

(\*) - Typical value for number of tests.

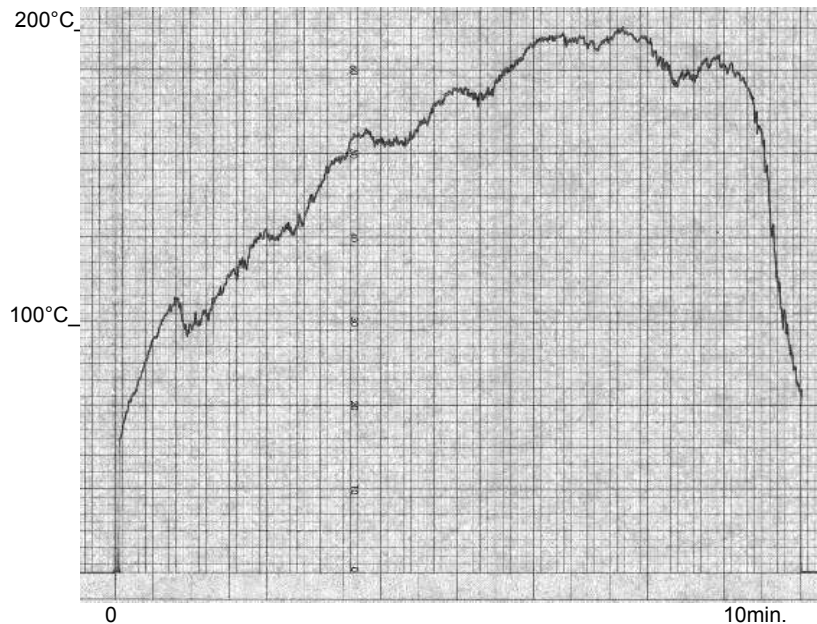


Fig.1. Example of heating tunnel profile for curing SC 65MN

### **ATTENTION:**

1. Product is ready for use, but should be mixed very thoroughly before use using wood or plastic spatula. Mix smoothly from the bottom of the container. Mix carefully - not to whip air into the product. ***INSURE ELPOX SC 65MN IS AT ROOM TEMPERATURE WHEN YOU WILL START WORKING WITH. Refrigeration during shelf time is not necessary.***
2. Prepare consistency before use according your SPECIFICATION.
3. If you need, use AXMC **65EM** thinner. Thinner will change paste resistivity. Pls, do not exceed 1% of weight. After first tests pls let us know about your viscosity requirements – we will be able to change it for you.
4. When quick curing time option is applied - post heating after curing process is recommended (ab.120°C during several minutes).
5. Low conductivity and poor adhesion performance are symptomatic that paste is under curing conditions.
6. Refrigeration during shelf time not necessary, but useful. Keep container with lacquer in temp. no less 10 C. Before use, increase paste temperature very slowly.
7. Use paste with adequate ventilation.
8. Avoid skin and eye contact. If ingested, consult a physician immediately.
9. Clean by MEK or other suitable solvents. Allow screen to completely dry before using again.
10. Temperature during printing process must be kept between 20°C and 25°C, with relative humidity (RH) between 40% and 65%. This condition reduces static charges on the substrate.
11. When stored – keep container closed.

This information is based on data and tests believed to be accurate. **AMEPOX MC** makes no warranties ( expressed or implied ) as to its accuracy and assumes no liability in connection with the use or inability to use this product.

( ex-sc65mn )